

# S-LESD8LL3.3T5G ESD PROTECTION DIODE

# **Discription**

The S-LESD8LL3.3T5G is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time,make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, digital cameras and many other portable applications where board space is at a premium.

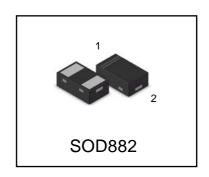
## **Applications**

- I Cellular phones audio
- I Digital cameras
- I Portable applications
- I Mobile telephone

### **Features**

- I Low Leakage
- I Response Time is Typically < 1 ns
- I ESD Rating of Class 3 per Human Body Model
- I IEC61000-4-2 Level 4 ESD Protection
- I We declare that the material of product compliant with RoHS requirements and Halogen Free.
- S-prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

# S-LESD8LL3.3T5G





### **Ordering information**

Device	Marking	Shipping
S-LESD8LL3.3T5G	Q7	10000/Tape&Reel

### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge Contact discharge		±16 ±16	kV kV
Total Power Dissipation on FR-5 Board (Note 1) @ $T_A$ =25 $^{\circ}$ C	PD	200	mW
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	$^{\circ}$ C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	$^{\circ}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0\*0.75\*0.62 in.

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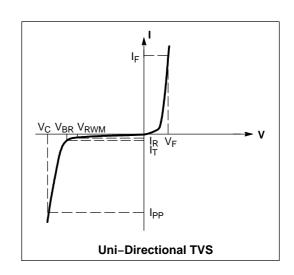


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#### **ELECTRICAL CHARACTERISTICS**

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>RWM</sub> Working Peak Reverse Voltage	
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
$V_{BR}$	Breakdown Voltage @ I <sub>T</sub>
I <sub>T</sub> Test Current	
I <sub>F</sub> Forward Current	
V <sub>F</sub> Forward Voltage @ I <sub>F</sub>	
P <sub>pk</sub>	Peak Power Dissipation
С	Capacitance @ V <sub>R</sub> = 0 and f = 1.0 MHz

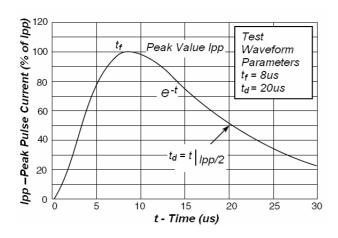


#### **ELECTRICAL CHARACTERISTICS**

	V <sub>RWM</sub> (V)	I <sub>R</sub> (μΑ) @ V <sub>RWM</sub>		(V) = 1 mA ote 1)	V <sub>C</sub> (V) @ I <sub>PP</sub> = 1 A (Note 2)	V <sub>C</sub> (V) @MAX I <sub>PP</sub> (Note 2)	Ipp(A) (Note 2)	P <sub>PK</sub> (W) (Note 2)	C	(pF)
Device	Max	Max	Min	Max	Max	Max	Max	Max	Тур	Max
S-LESD8LL3.3T5G	3.3	0.5	4.5	7.8	10	14	5	70	0.5	0.6

Other voltage available upon request.

- 1.  $V_{BR}$  is measured with a pulse test current IT at an ambient temperature of 25  $^{\circ}{\!\!\!^{\circ}}{\!\!\!^{\circ}}$
- 2. Surge current waveform per Figure 1.



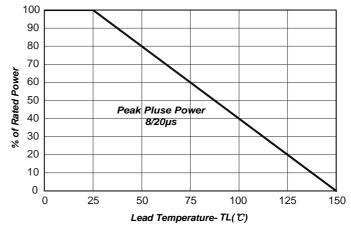


Fig1. Pulse Waveform

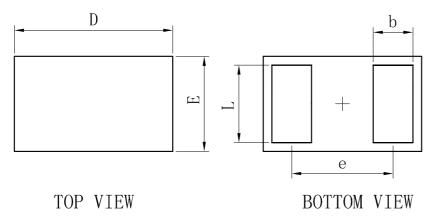
Fig2.Power Derating Curve

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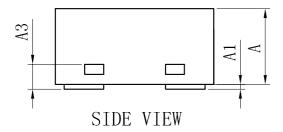


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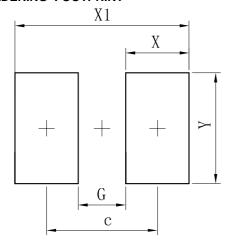
### **OUTLINE AND DIMENSIONS**



S0D882				
Dim	Min	Тур	Max	
D	0. 95	1.00	1.05	
Е	0. 55	0.60	0.65	
е	_	0.64	-	
L	0.44	0.49	0. 54	
b	0.20	0. 25	0.30	
A	0.43	0.48	0. 53	
A1	0	_	0.05	
А3	0. 127REF.			
All Dimensions in mm				



### **SOLDERING FOOTPRINT**



Dimensions	(mm)
С	0.70
G	0.30
X	0.40
X1	1. 10
Y	0.70

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